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DATA SHEET

BFT25
NPN 2 GHz wideband transistor

Product specification

November 1992

NPN 2 GHz wideband transistor BFT25

DESCRIPTION

NPN transistor in a plastic SOT23 envelope.

It is primarily intended for use in RF low power amplifiers, such as in pocket phones, paging systems, etc. The transistor features low current consumption (100 μA to 1 mA); due to its high transition frequency, it also has excellent wideband properties and low noise up to high frequencies.

PINNING

PIN	DESCRIPTION
Code: V1p	
1	base
2	emitter
3	collector

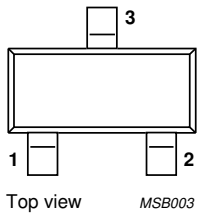


Fig.1 SOT23.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	8	V
V_{CEO}	collector-emitter voltage	open base	–	5	V
I_c	DC collector current		–	6.5	mA
P_{tot}	total power dissipation	up to T_s = 167 °C; note 1	–	30	mW
f_T	transition frequency	I_C = 1 mA; V_{CE} = 1 V; f = 500 MHz; T_{amb} = 25 °C	2.3	–	GHz
C_{re}	feedback capacitance	I_C = 1 mA; V_{CE} = 1 V; f = 1 MHz; T_{amb} = 25 °C	–	0.45	pF
G_{UM}	maximum unilateral power gain	I_C = 1 mA; V_{CE} = 1 V; f = 500 MHz; T_{amb} = 25 °C	18	–	dB
F	noise figure	I_C = 1 mA; V_{CE} = 1 V; f = 500 MHz; T_{amb} = 25 °C	3.8	–	dB

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	8	V
V_{CEO}	collector-emitter voltage	open base	–	5	V
V_{EBO}	emitter-base voltage	open collector	–	2	V
I_C	DC collector current		–	6.5	mA
I_{CM}	peak collector current	f > 1 MHz	–	10	mA
P_{tot}	total power dissipation	up to T_s = 167 °C; note 1	–	30	mW
T_{stg}	storage temperature		−65	150	°C
T_j	junction temperature		–	175	°C

Note

1. T_s is the temperature at the soldering point of the collector tab.

THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	THERMAL RESISTANCE
$R_{th\ j\text{-}s}$	thermal resistance from junction to soldering point	up to T_s = 167°C; note 1	260 K/W

Note

1. T_s = is the temperature at the soldering point of the collector tab.

CHARACTERISTICS

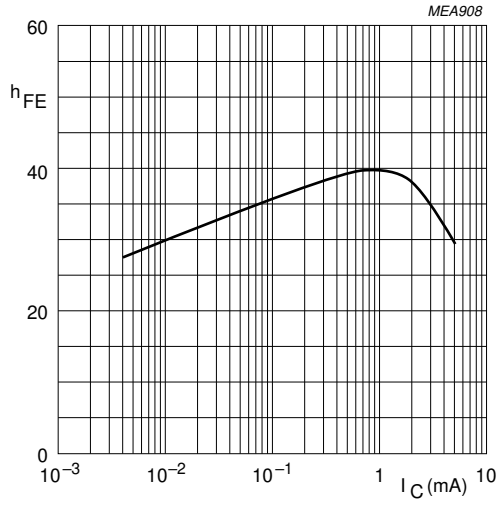
T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector cut-off current	I_E = 0; V_{CB} = 5 V	–	–	50	nA
h_{FE}	DC current gain	I_C = 10 μA; V_{CE} = 1 V	20	30	–	
		I_C = 1 mA; V_{CE} = 1 V	20	40	–	
f_T	transition frequency	I_C = 1 mA; V_{CE} = 1 V; f = 500 MHz	1.2	2.3	–	GHz
C_c	collector capacitance	$I_E = i_e$ = 0; V_{CB} = 0.5 V; f = 1 MHz	–	–	0.6	pF
C_e	emitter capacitance	$I_c = i_c$ = 0; V_{EB} = 0; f = 1 MHz	–	–	0.5	pF
C_{re}	feedback capacitance	I_C = 1 mA; V_{CE} = 1 V; f = 1 MHz; T_{amb} = 25 °C	–	–	0.45	pF
G_{UM}	maximum unilateral power gain (note 1)	I_C = 1 mA; V_{CE} = 1 V; f = 500 MHz; T_{amb} = 25 °C	–	18	–	dB
		I_C = 1 mA; V_{CE} = 1 V; f = 800 MHz; T_{amb} = 25 °C	–	12	–	dB
F	noise figure	I_C = 0.1 mA; V_{CE} = 1 V; f = 500 MHz; T_{amb} = 25 °C	–	5.5	–	dB
		I_C = 1 mA; V_{CE} = 1 V; f = 500 MHz; T_{amb} = 25 °C	–	3.8	–	dB

Note

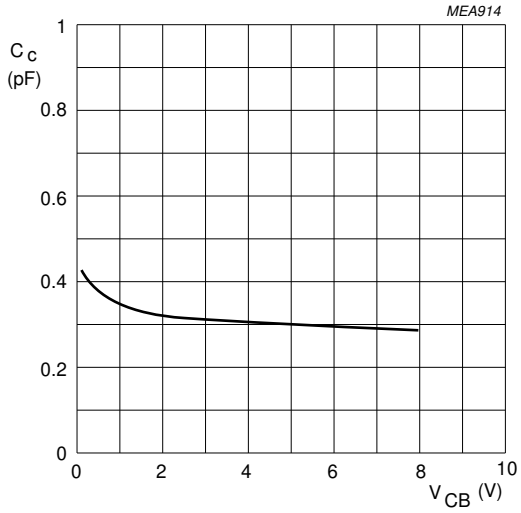
1. G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero and

$$G_{UM} = 10 \log \frac{|S_{21}|^2}{(1-|S_{11}|^2)(1-|S_{22}|^2)} \text{dB}.$$



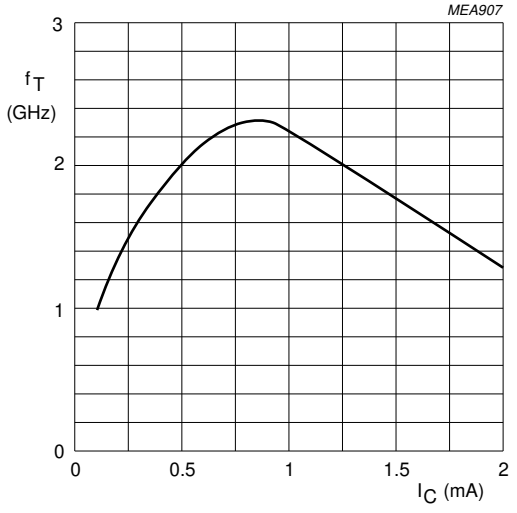
V_{CE} = 1 V; T_j = 25 °C.

Fig.2 DC current gain as a function of collector current.



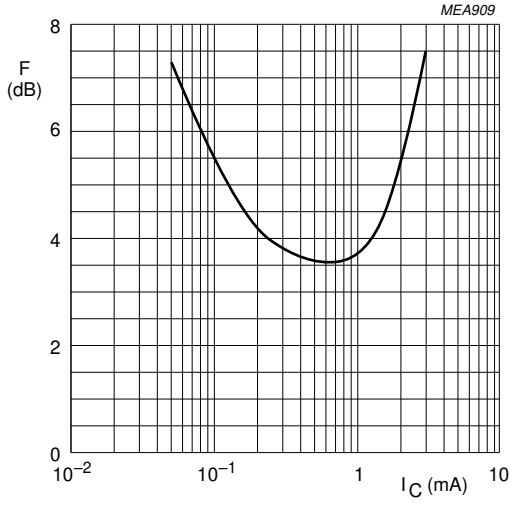
$I_E = i_e$ = 0; f = 1 MHz; T_j = 25 °C.

Fig.3 Collector capacitance as a function of collector-base voltage.



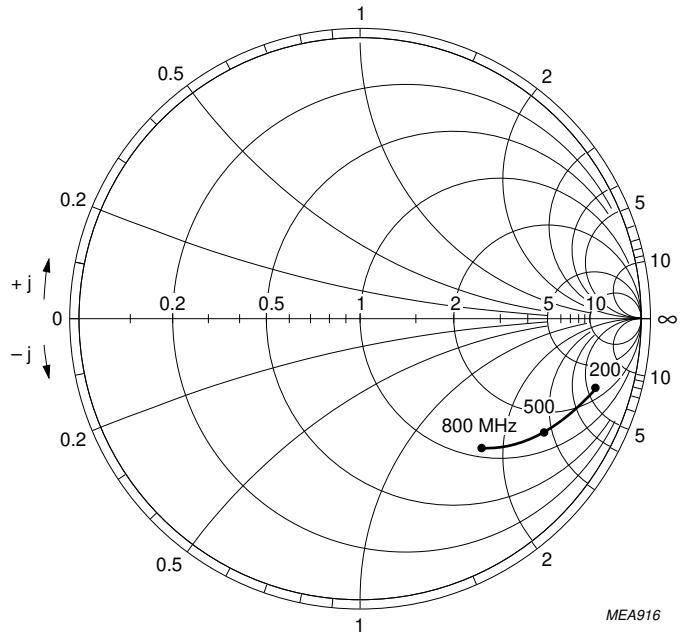
V_{CE} = 1 V; f = 500 MHz; T_j = 25 °C.

Fig.4 Transition frequency as a function of collector current.



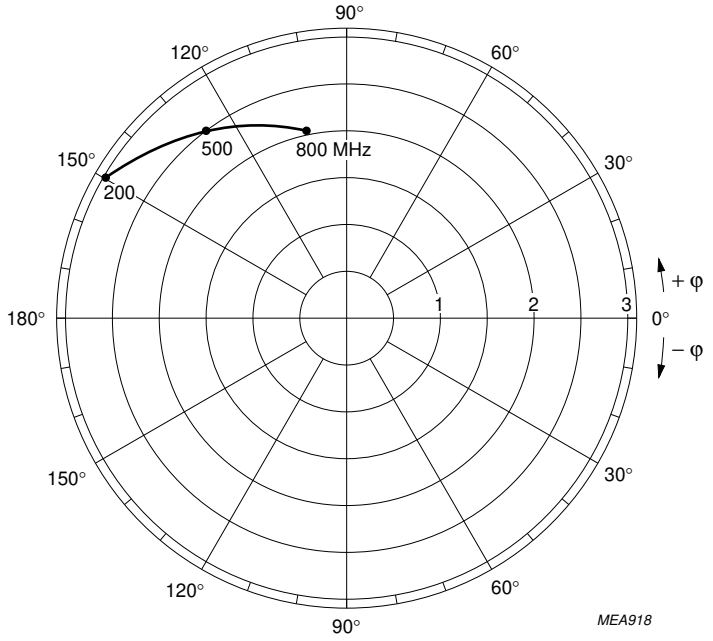
V_{CE} = 1 V; Z_S = opt.; f = 500 MHz; T_{amb} = 25 °C.

Fig.5 Minimum noise figure as a function of collector current.



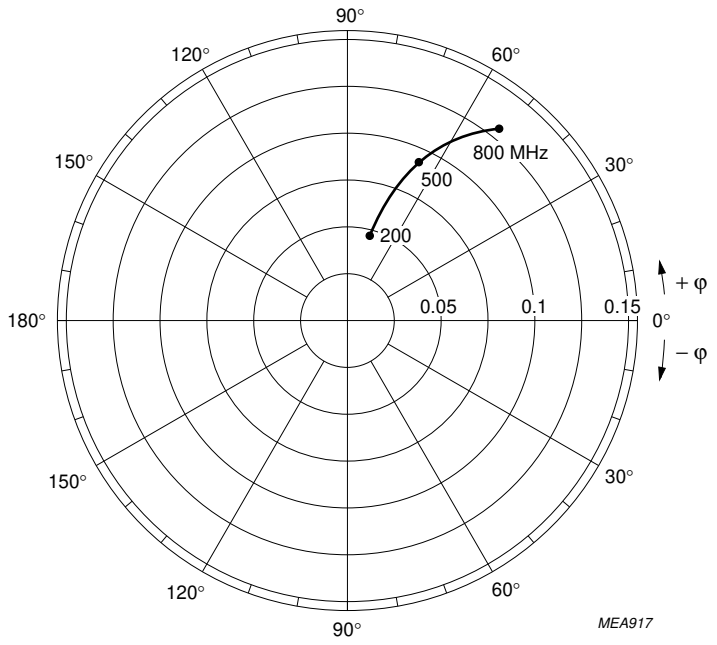
I_C = 1 mA; V_{CE} = 1 V; T_{amb} = 25 °C.
Z_o = 50 Ω.

Fig.6 Common emitter input reflection coefficient (S_{11}).



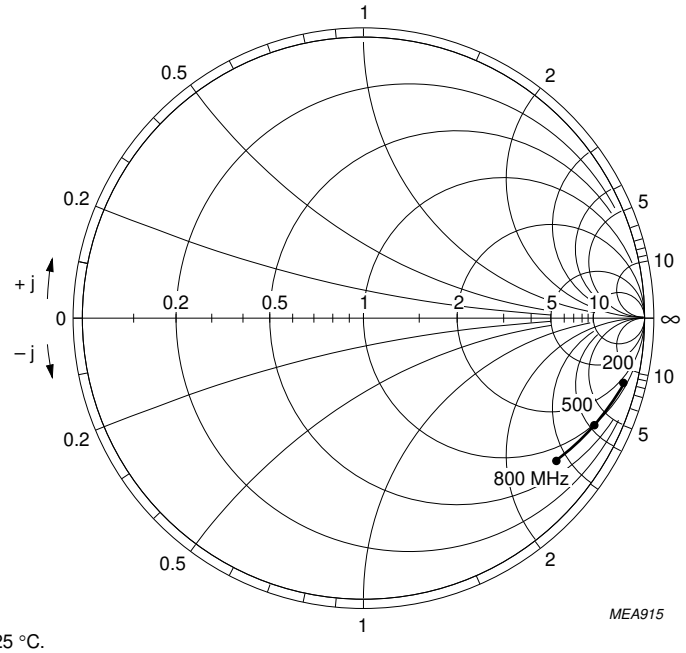
I_C = 1 mA; V_{CE} = 1 V; T_{amb} = 25 °C.

Fig.7 Common emitter forward transmission coefficient (S_{21}).



I_C = 1 mA; V_{CE} = 1 V; T_{amb} = 25 °C.

Fig.8 Common emitter reverse transmission coefficient (S_{12}).

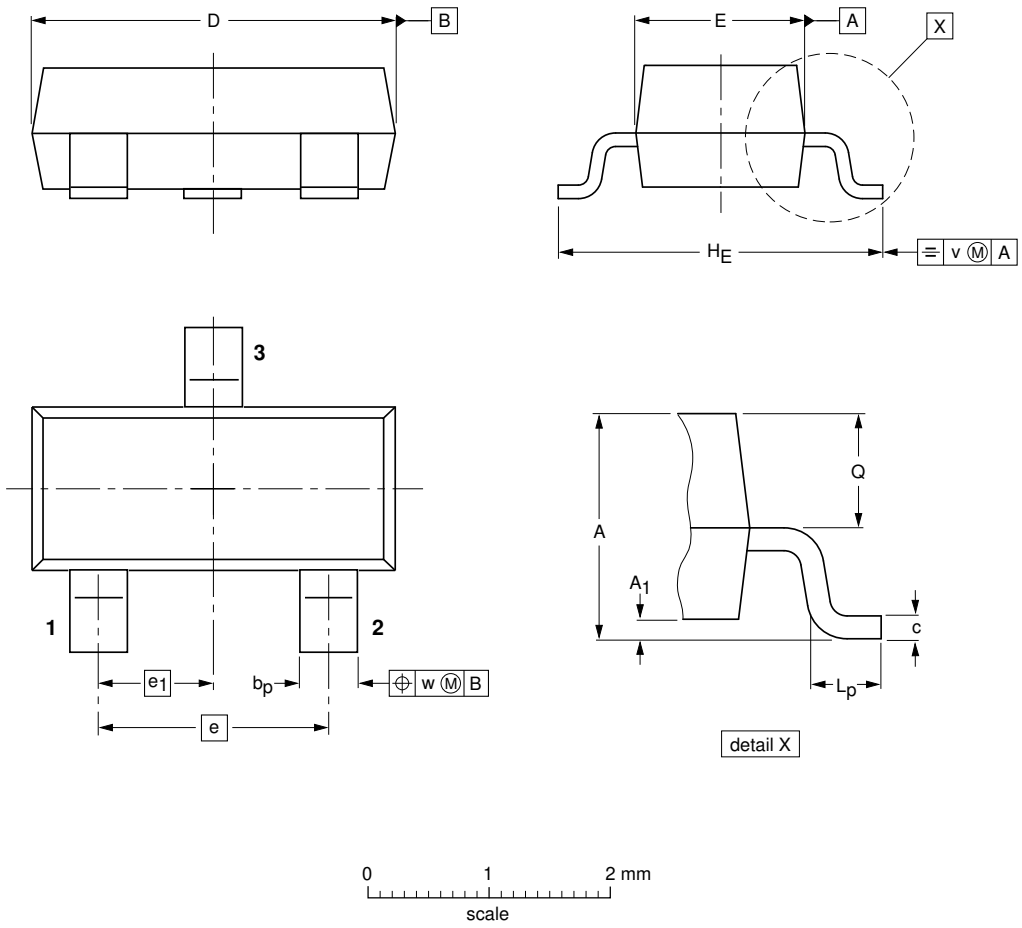


I_C = 1 mA; V_{CE} = 1 V; T_{amb} = 25 °C.
Z_o = 50 Ω.

Fig.9 Common emitter output reflection coefficient (S_{22}).

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads **SOT23**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max.	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT23		TO-236AB				~~04-11-04~~ 06-03-16

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Contact information

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